

**S/N 10/612,764**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Vassoudevane Lebonheur et al.

Examiner: Victor A. Mandala

Serial No.: 10/612,764

Group Art Unit: 2826

Filed: June 30, 2003

Docket No.: 884.862US1

Title: MOLD COMPOUND CAP IN A FLIP CHIP  
MULTI-MATRIX ARRAY PACKAGE AND PROCESS  
OF MAKING SAME

Customer Number: 21186

**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This responds to the Office Action mailed on March 13, 2006. Please amend the above-identified patent application as follows.